

**In the Specification:**

In the section titled "BRIEF DESCRIPTION OF THE DRAWINGS", please delete the section and insert the following:

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--FIG. 1A is a schematic cross section of a low profile high power ball grid array device as an embodiment of the present invention

B<sup>1</sup> FIG. 1B is a schematic cross section of the device of Figure 1A attached to a printed circuit board.

FIG. 1C is a schematic cross section of the device of Figure 1B attached to a printed circuit board including a heatsink.

FIG. 2 is a magnified cross section of a portion of an actual device illustrating key features of the present invention.

FIG. 3A is a magnified top view of a portion of the mounted chip on a substrate fabricated according to the present invention.

FIG. 3B is a highly magnified top view of a portion of the mounted chip on a substrate fabricated according to the present invention.

FIGs. 4 to 12 are schematic and simplified perspective views of plastic tape portions illustrating individual process steps in the fabrication flow of the reel-to-reel tape used in the assembly of the semiconductor devices according to the invention.

FIGs. 13 to 16 are schematic and simplified perspective views of a chip illustrating individual process steps in the assembly and packaging flow of the chip towards a ball grid array type device, as an example of an embodiment of the invention.--

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*On page 6 of the specification, in the second paragraph, delete that paragraph and insert the following:*

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B<sup>2</sup> --In the schematic cross section of FIG. 1A, a low profile ball grid array package, generally designated 100, for high power dissipation is shown as an

embodiment of the present invention. The device comprises a plastic tape 101, which has a first surface 101a and a second surface 101b. The first surface 101a is at least partially covered with an adhesive layer (not shown on FIG. 1) so that other materials such as a metal foil can be attached to it. As can be seen in FIG. 1A, tape 101 (and the adhesive layer) has a plurality of first openings of diameter 102. These first openings are preferably circular and configured so that each opening can be used for one solder ball 103.—

*[On page 6 of the specification, in the third paragraph, delete that paragraph and insert the following:]*

B<sup>2</sup>  
Cont.

--Furthermore, tape 101 has at least one second opening of width 104. This second opening is preferably shaped as a rectangle or a square and has dimensions somewhat larger than the dimensions of the integrated circuit chip 106 of device 100 (more detail in FIG. 2). In the preferred embodiment shown in FIG. 1A, there is only one opening of the second kind; it should be pointed out, though, that in other embodiments of the invention, the tape may have two or more openings of the second kind in order to accommodate multi-chip modules.--

*[On page 6 of the specification, in the fourth paragraph, delete that paragraph and insert the following:]*

--A metal foil 105, preferably copper, is laminated on the adhesive layer covering portions of the first surface 101a of tape 101. As can be seen in FIG. 1A, this metal foil 105 covers the first openings of diameter 102 and thus enables the attachment of solder balls 103. A portion of metal foil 105 also covers the second opening of width 104.--

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*On page 7 of the specification, in the first paragraph, delete that paragraph and insert the following:*